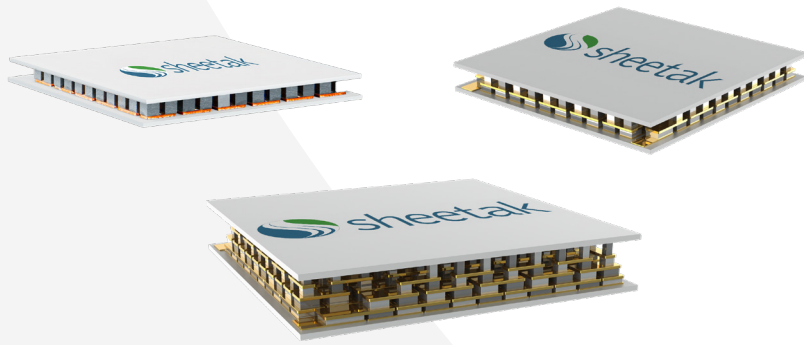




Best-in-class Thermoelectric coolers

CENTUM® C3 delivers **industry-leading temperature difference** and **cooling density** with the thickness of a single-stage chip, leveraging patented multi-stage architecture and compact form factors

1.2x | Temperature Difference

2x | Cooling Density

Deep cooling across multiple applications

Optoelectronics



Optical Transceivers
Pump Lasers

Imaging Sensors



IR/CCD/CMOS
LiDAR
AR/VR

Refrigeration



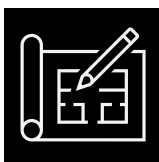
Consumer
Medical
Industrial

Others



Instrumentation
Aerospace/Defense

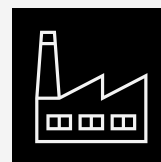
Contact us for all your TEC needs



Custom design



Rapid prototyping



Made in USA

Standard available models

	<i>Dimensions</i> (mm)	<i>T_h</i> (°C)	<i>ΔT_{max}</i> (°C)	<i>Q_{max}</i> (Watts)	<i>I_{max}</i> (Amps)	<i>V_{max}</i> (DC Volts)	<i>R_{AC}</i> (Ω)
CENTUM C3-22-22-7	10x12.8x2.8	27	97	3.0	7.1	1.9	0.23
		50	110	3.7	7.0	2.1	
CENTUM C3-38-38-7	13x16x2.8	27	97	5.3	7.1	3.4	0.41
		50	110	6.6	7.0	3.8	
CENTUM C3-71-71-7	22x22x2.8	27	97	10	7.1	6.25	0.78
		50	110	13	7.0	6.95	
CENTUM C3-127-127-7	29x29x3.3	27	97	18	7.1	11.4	1.5
		50	110	22	7.0	12.7	
CENTUM C3-238-238-7	40x40x3.7	27	97	34	7.1	22	2.7
		50	110	42	7.0	24	

Customization options

Substrate

Ceramic (ALN)

Ceramic (ALO)

Metal

Finishing

Sealing/Lapping

Substrate Metalization

Lead Attachment

Design

Form Factors

System Integration

System Optimization